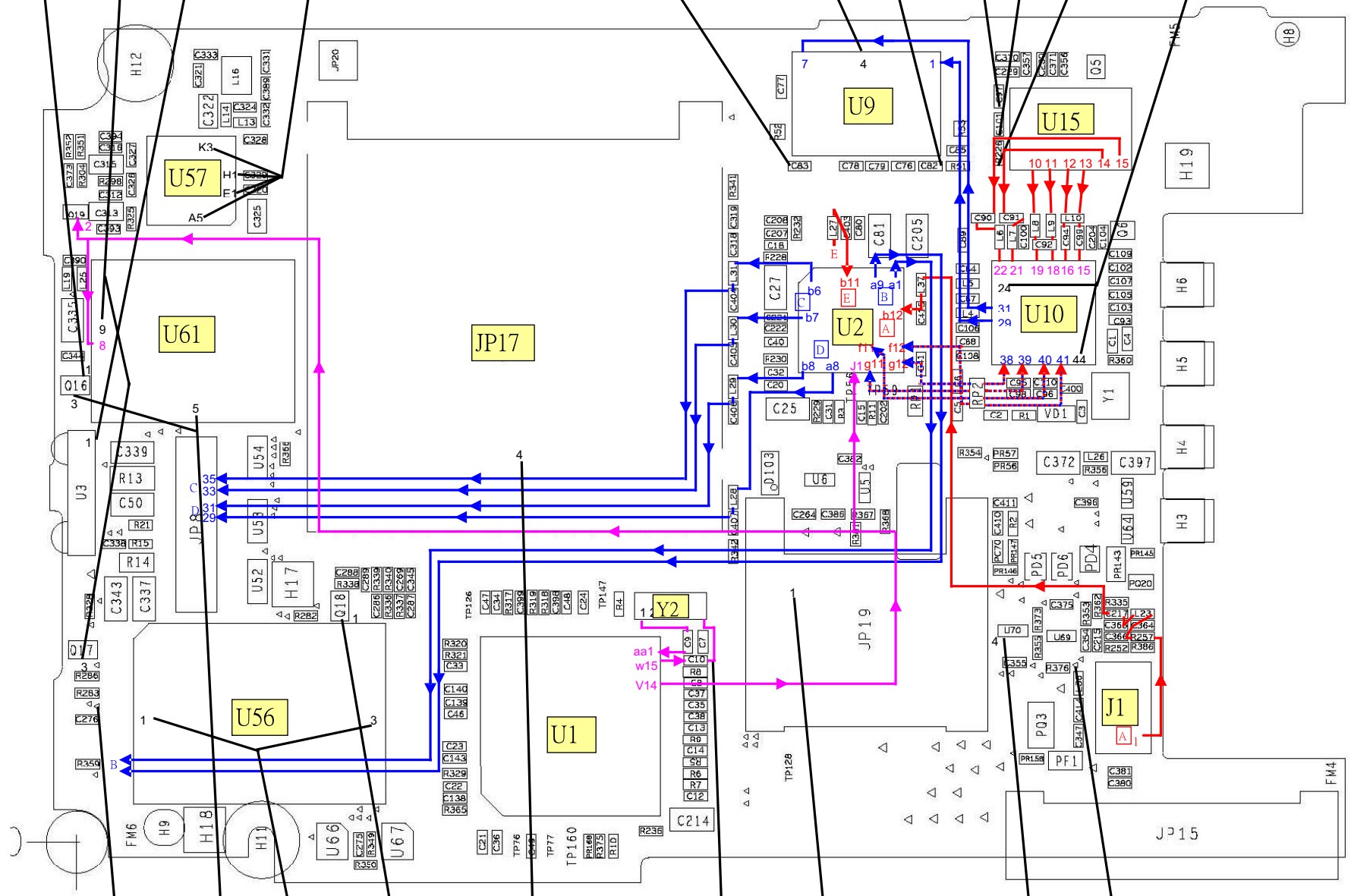


N\_WLAN\_en V\_IP8(WLAN) DC\_PWR(IrDA) V\_BT TSPACT03 Vbat Vramp TSPACT02 TSPACT01 TSPACT04 DC\_PWR(Trancever)

A: Internal MIC signal  
 B: Headset signal  
 C: Speaker signal  
 D: Receiver signal  
 E: Hadset microphone signal

Band Switch	TX850/900	TX1800/1900	RX850
CTRL1(TSPACT02)	2.8V	0V	0V
CTRL2(TSPACT01)	0V	2.8V	0V
CTRL3(TSPACT04)	0V	0V	2.8V
All 0V RX900/RX1800/RX1900			

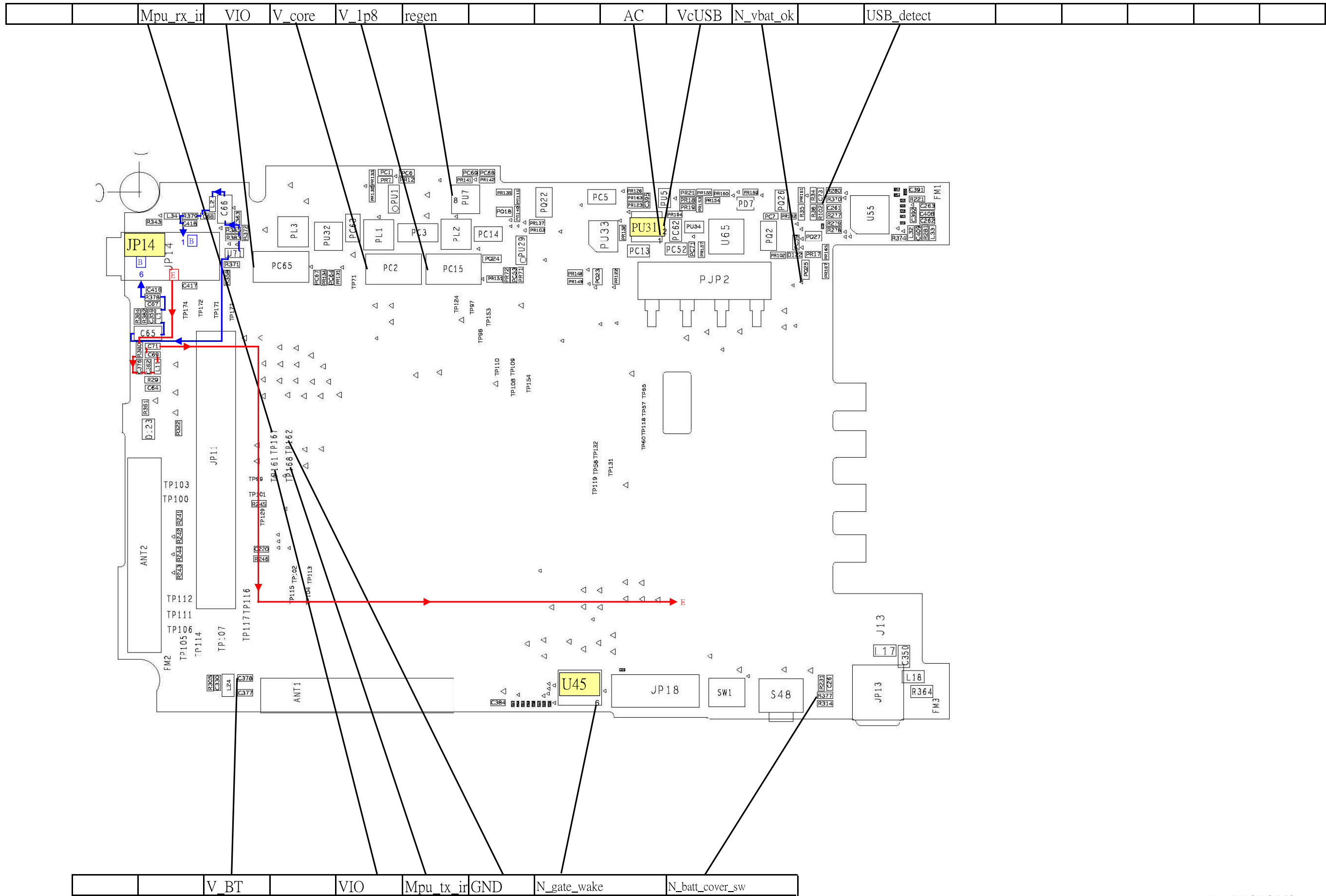


n\_FCS3 VIO(WLAN) n\_SD\_pwr\_e VIO (SD) 32KHz V\_SIM N\_pwon N\_mpu\_rst



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LCD\_5V | I2C I/F | SPI I/F | SUB\_BL\_EN | LCD\_BL\_EN | V2P5 | CAM\_EXCLK | CAM\_LCLK | CAM\_LIGHT\_EN

A. Speaker Path  
B. Receiver Path

N\_LCD\_3V\_EN | LCD\_5V\_EN | LCD\_PCLK | LCD\_AC | LCD\_VEEVDD\_EN | VIBRATOR\_EN | V3P3 | N\_DIS\_BACKUP\_BATT | N\_SPK\_SD



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